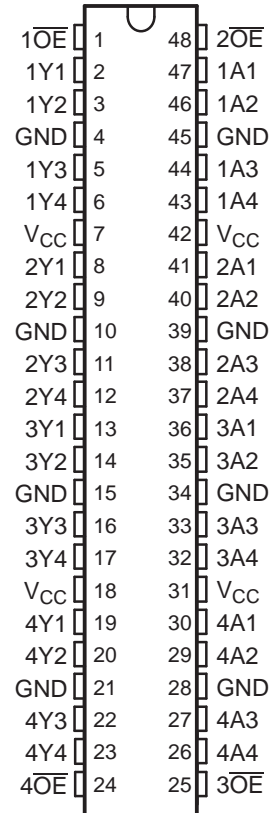


FEATURES

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Output Ports Have Equivalent 22-Ω Series Resistors, So No External Resistors Are Required
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVT162240 . . . WD PACKAGE
SN74LVT162240 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The 'LVT162240 devices are 16-bit buffers/drivers designed specifically for low-voltage (3.3-V) V_{CC} operation and to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. They have the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer and provide inverting outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 22-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

SN54LVT162240, SN74LVT162240
3.3-V ABT 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

SCBS719A–JULY 2000–REVISED NOVEMBER 2006

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVT162240 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LVT162240 is characterized for operation from -40°C to 85°C .

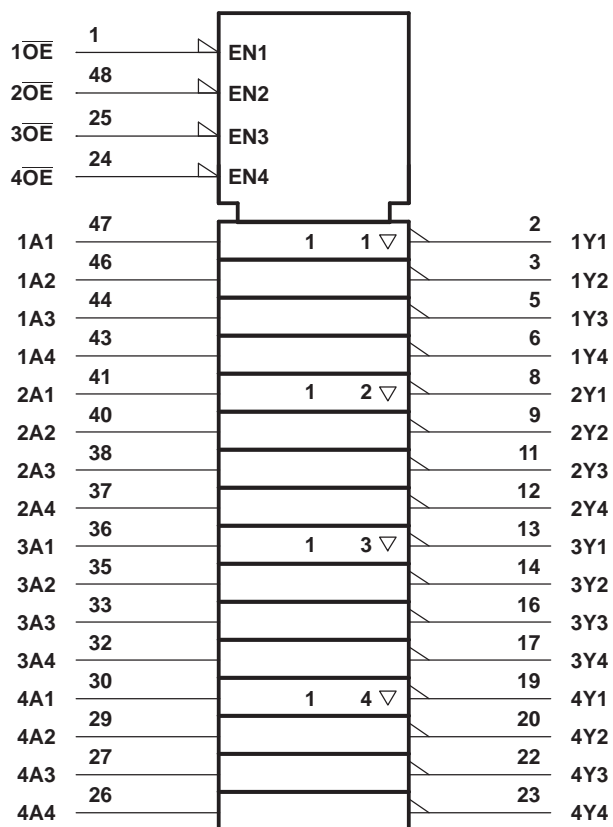
ORDERING INFORMATION

T_A	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	SSOP – DL	Reel of 1000	74LVT162240DLRG4	
			SN74LVT162240DLR	
		Tube of 25	SN74LVT162240DL	LVT162240
			SN74LVT162240DLG4	
	TSSOP – DGG	Reel of 2000	74LVT162240DGGRE4	LVT162240
			SN74LVT162240DGGR	
	TVSOP – DGV	Reel of 2000	74LVT162240DGVRE4	LZ240
			SN74LVTH162240DGVR	

FUNCTION TABLE
(each 4-bit buffer/driver)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	L
L	L	H
H	X	Z

LOGIC SYMBOL⁽¹⁾

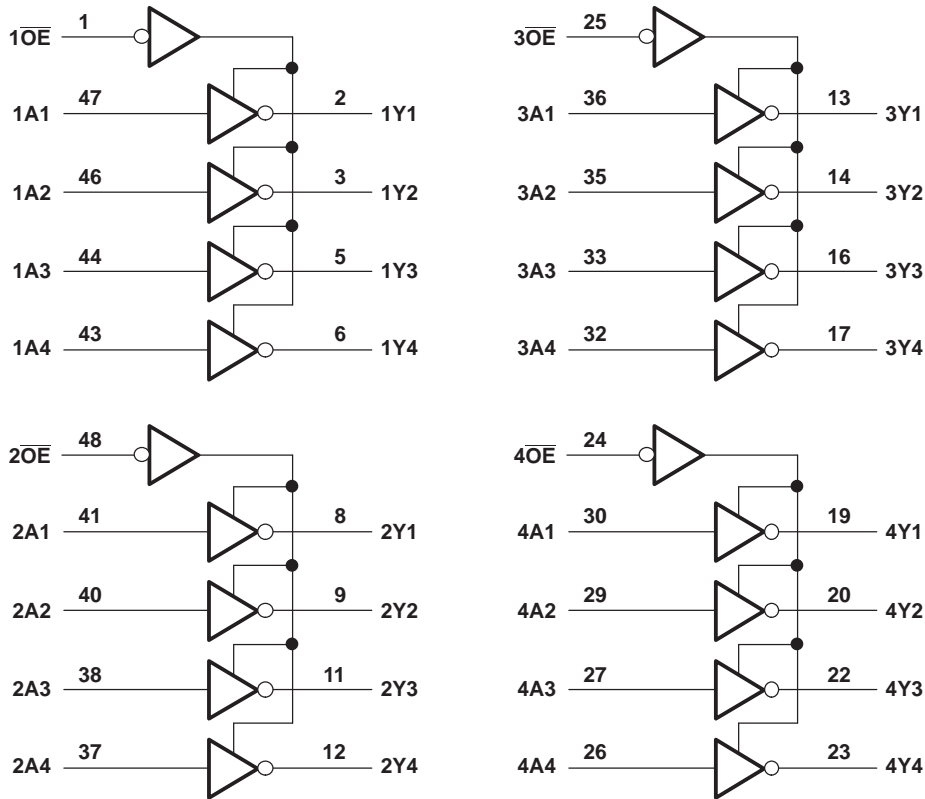


(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SN54LVT162240, SN74LVT162240
3.3-V ABT 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high state ⁽²⁾	-0.5	$V_{CC} + 0.5$	V
I_O	Current into any output in the low state		30	mA
I_O	Current into any output in the high state ⁽³⁾		30	mA
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package	70	°C/W
		DGV package	58	
		DL package	63	
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This current flows only when the output is in the high state and $V_O > V_{CC}$.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

Recommended Operating Conditions⁽¹⁾

		SN54LVT162240		SN74LVT162240		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2.7	3.6	2.7	3.6	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage		5.5		5.5	V
I _{OH}	High-level output current		-12		-12	mA
I _{OL}	Low-level output current		12		12	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate	200		200		μs/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54LVT162240			SN74LVT162240			UNIT
		MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	
V _{IK}	V _{CC} = 2.7 V, I _I = -18 mA			-1.2			-1.2	V
V _{OH}	V _{CC} = 3 V, I _{OH} = -12 mA	2			2			V
V _{OL}	V _{CC} = 3 V, I _{OL} = 12 mA			0.8			0.8	V
I _I	V _{CC} = 0 or 3.6 V, V _I = 5.5 V			10			10	μA
	Control inputs V _{CC} = 3.6 V, V _I = V _{CC} or GND			±1			±1	
	Data inputs V _{CC} = 3.6 V			1			1	
				-5			-5	
I _{off}	V _{CC} = 0, V _I or V _O = 0 to 4.5 V						±100	μA
I _{OZH}	V _{CC} = 3.6 V, V _O = 3 V			5			5	μA
I _{OZL}	V _{CC} = 3.6 V, V _O = 0.5 V			-5			-5	μA
I _{OZPU}	V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE = don't care			±100 ⁽²⁾			±100	μA
I _{OZPD}	V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE = don't care			±100 ⁽²⁾			±100	μA
I _{CC}	V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		0.19	0.19		mA	
		Outputs low		5	5			
		Outputs disabled		0.19	0.19			
ΔI _{CC} ⁽³⁾	V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND			0.2			0.2	mA
C _i	V _I = 3 V or 0			4			4	pF
C _o	V _O = 3 V or 0			9			9	pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

(3) This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54LVT162240, SN74LVT162240
3.3-V ABT 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

SCBS719A–JULY 2000–REVISED NOVEMBER 2006

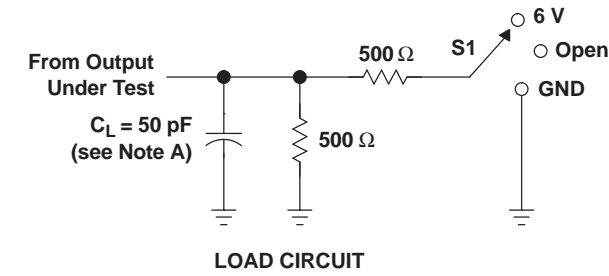
Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 1](#))

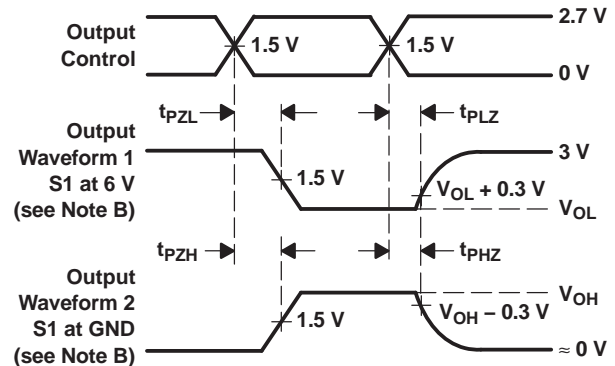
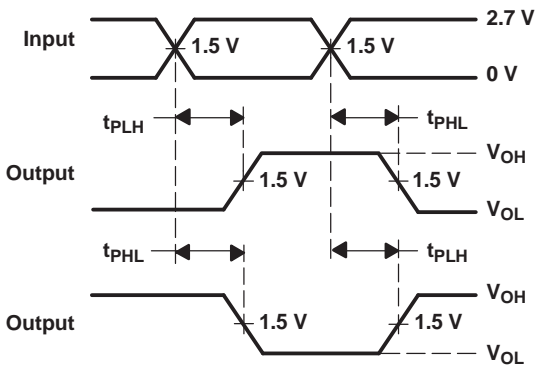
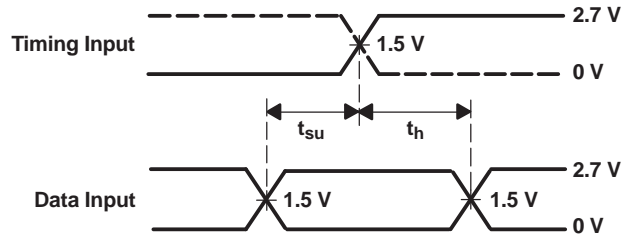
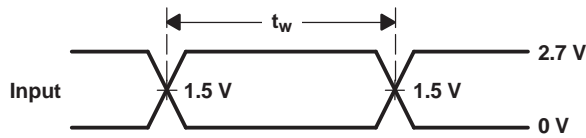
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT162240				SN74LVT162240				UNIT	
			$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP ⁽¹⁾	MAX	MIN		MAX
t_{PLH}	A	Y	1	4.2	5		1	2.5	4	4.6		ns
t_{PHL}			1	4.2	5		1	2.9	4	4.6		
t_{PZH}	\overline{OE}	Y	1	5	5.5		1	2.8	4.8	5.7		ns
t_{PZL}			1	4.9	5.1		1	2.8	4.7	4.9		
t_{PHZ}	\overline{OE}	Y	1.9	4.9	5.4		2	3.5	4.7	5.2		ns
t_{PLZ}			1.9	4.7	4.8		2	3.4	4.5	4.5		
$t_{sk(LH)}$								0.5			ns	
$t_{sk(HL)}$								0.5				

(1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVT162240DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT162240	Samples
SN74LVT162240DGVR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LZ240	Samples
SN74LVT162240DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT162240	Samples
SN74LVT162240DLG4	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVT162240	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT162240DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74LVT162240DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT162240DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74LVT162240DGVR	TVSOP	DGV	48	2000	853.0	449.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LVT162240DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74LVT162240DLG4	DL	SSOP	48	25	473.7	14.24	5110	7.87

MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.

DGV (R-PDSO-G**)

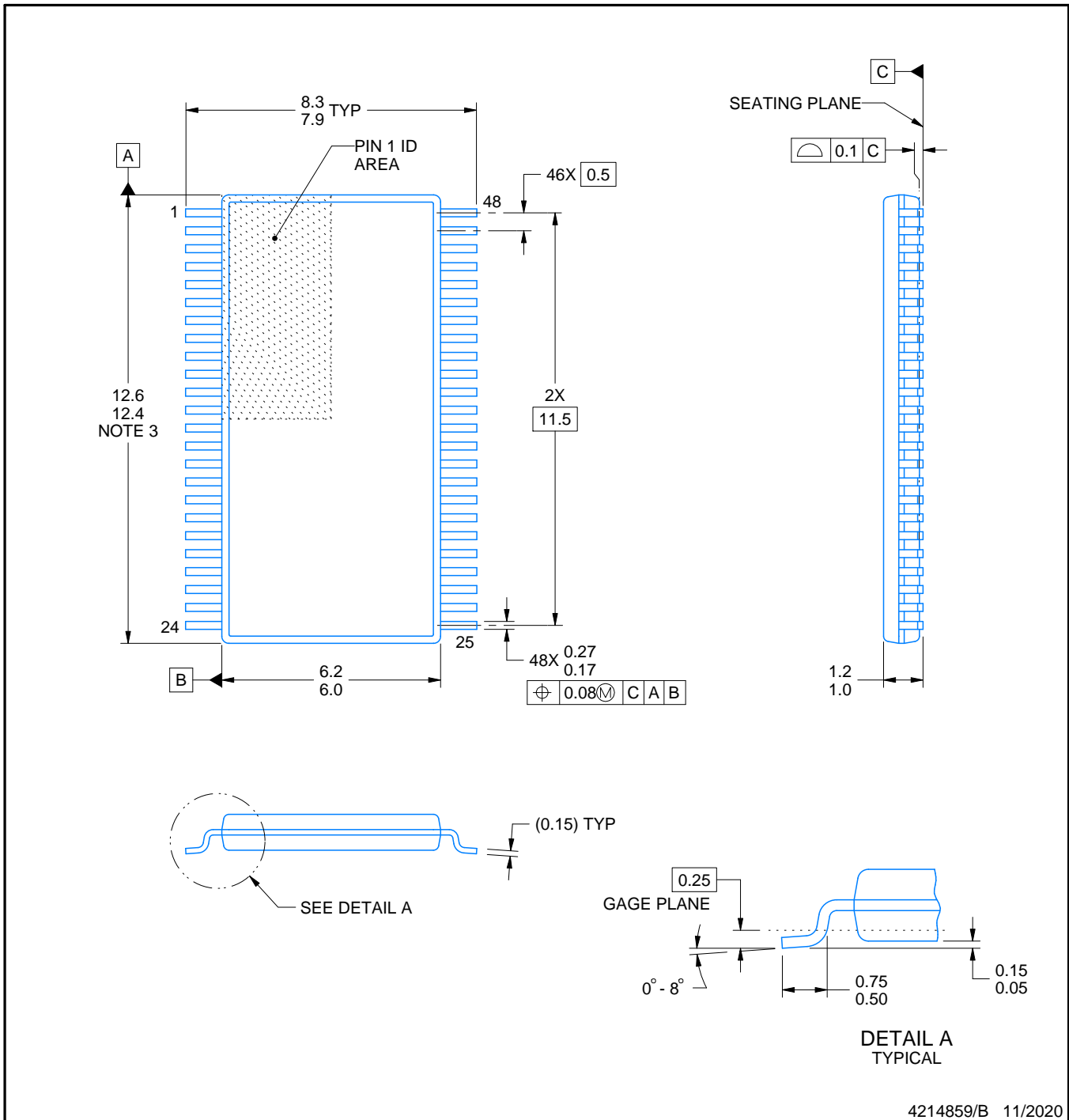
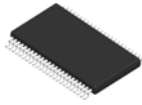
PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194



4214859/B 11/2020

NOTES:

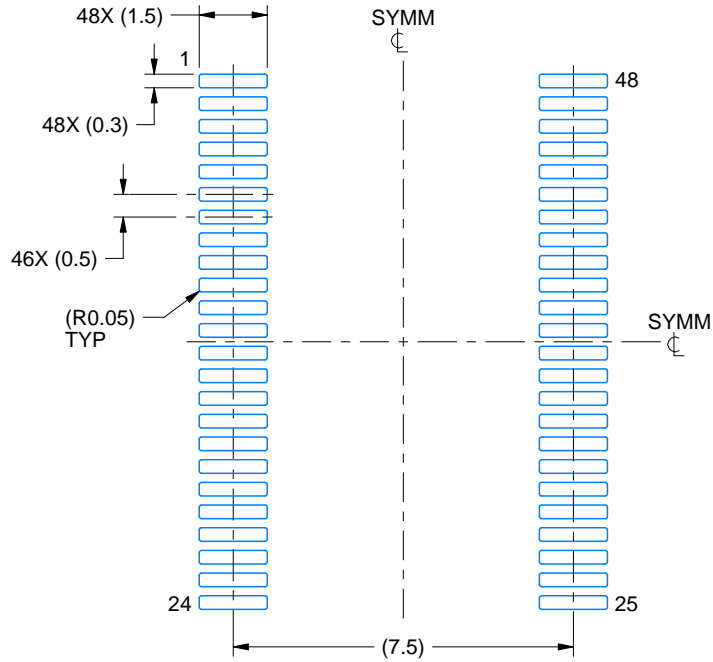
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

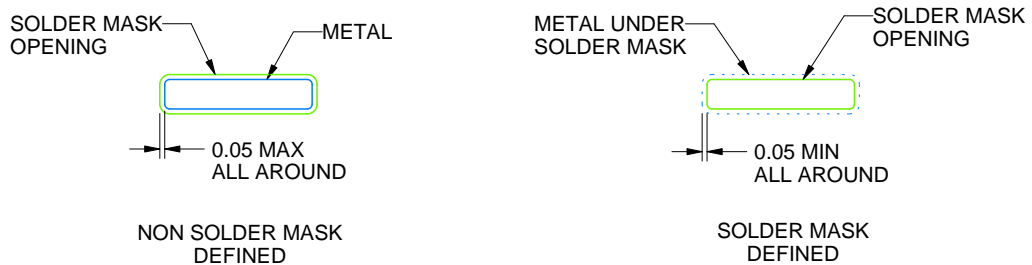
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

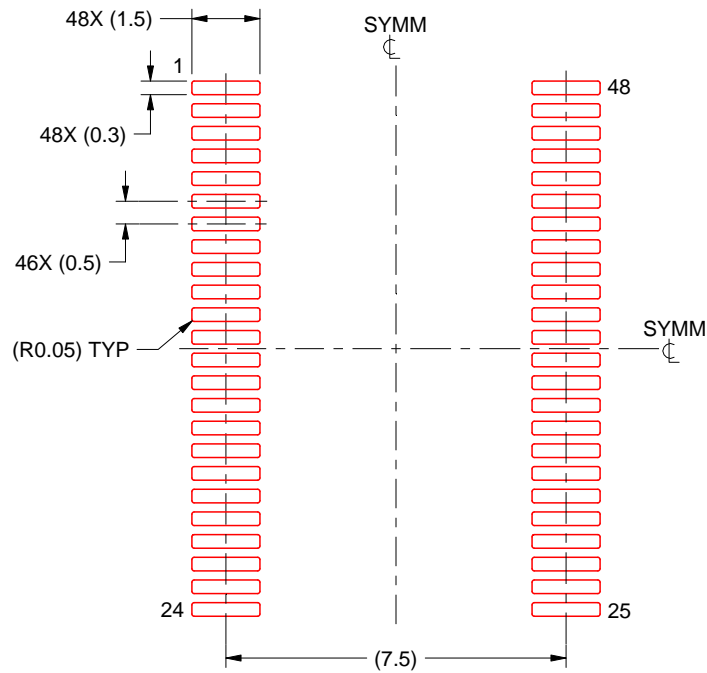
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B 11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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